



DOCKET NO: 251598US0

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :  
YUKIO HOSAKA, ET AL. : EXAMINER: RACHUBA, MAURINA T.  
SERIAL NO: 10/820,123 :  
FILED: APRIL 8, 2004 : GROUP ART UNIT: 3723  
FOR: ABRASIVE PAD, METHOD AND :  
METAL MOLD FOR MANUFACTURING :  
THE SAME, AND SEMICONDUCTOR :  
WAFER POLISHING METHOD :

AMENDMENT AND REQUEST FOR RECONSIDERATION

COMMISSIONER FOR PATENTS  
ALEXANDRIA, VIRGINIA 22313

SIR:

In response to the Official Action dated April 12, 2007, reconsideration is respectfully requested in the above-identified application in view of the following amendments and remarks:

**Amendments to the Claims** begin on page 2 of this response.

**Support for the Amendments** begin on page 7 of this response.

**Remarks** begin on page 8 of this response.

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